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# GOMACTech-16

*“More Than Moore and Beyond”*

Wyndham Orlando Resort International  
Orlando, FL

14 -17 March 2016

## Second Call for Papers

The conference theme for 2016 is “More than Moore and Beyond.” A dwindling number of commercial foundries have chosen to continue to pursue scaling digital integrated circuit technologies to the lowest physical limit. However, this doesn’t mean that other foundries and design houses will stagnate. Innovative strategies are being developed to gain additional performance using well established silicon technologies as a substrate for integrating additional non-Si technologies. These strategies include technologies based on different state variables, molecular electronics, photons, phonons, plasmons, RF photonics, and quantum. New materials, such as meta materials and nanostructures, will play an important role. Advances will be enabled by hetero-integration of different technologies in 3D-stacking, which reduces the parasitic impedance, size, weight and power. With the integration of different technologies comes new systems of systems, and the discovery of new phenomena beyond the limits of Moore’s Law.

GOMACTech-16 provides a forum for discussing and demonstrating advanced microelectronics and microsystems that can provide the means to develop confidence in transformational, leap-ahead technologies and capabilities. GOMACTech is the premier forum for reporting on government funded micro- circuit research and other research efforts that focus on the technology needs of government systems. It is an unclassified, export- controlled event. All registrants must provide proof of U.S. citizenship or permanent residence status and sign a non-disclosure statement prior to being permitted entry into the conference.

- Trust, Security, and Counterfeit Technologies
- Advances in Materials & Devices
- Advanced Microelectronics & Microsystems
- Heterogeneous 3-D Systems
- Quantum Science and Engineering
- Neuroelectronics
- Reconfigurable Electronics
- Power Electronics & Emerging Power Technologies
- Very Low-Power Electronics
- RF Components, Technologies, and Applications
- Phased Arrays
- Flexible & Transient Electronics
- Radiation Hardened Technologies, Designs & Systems

• Electronic Abstracts Due <a href="http://www.gomactech.net/">http://www.gomactech.net/</a>	September 11, 2015
• Author Notification of Acceptance	November 4, 2015
• Final Paper Due	January 8, 2016

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